# **TF-2010G**

# SERIES 2 Y70 LASER TRIMMER



# A New Generation Platform for Trim and Test Thick Film Components Size of 0201 / 01005 and Circuits

- Advanced vision and motion subsystems provide dramatically improved positioning and alignment capability
- Capability to trim from ohms ( $\Omega$ ) to Mega-ohms ( $M\Omega$ )
- Built-in pattern recognition for auto compensation & precise alignment
- Ability to trim substrates with resistors sizes of 0201 (0.02"X0.01") and 01005 (0.01" X 0.005")
- · User friendly GUI software
- . Theta adjustment for clamping device for precise alignment
- Intelligent sensors to detect and isolate part defects
- Twin magazines to store additional substrates and reduce machine idle time.

# TF-2010G SERIES 2 Y70 LASER TRIMMER - SPECIFICATIONS

# **Optical System**

Beam Positioned: Precision high-speed\_galvanometer

Field Size: 12 x 75mm
Resolution: 1.5μm
Repeatability: 2.5 μm

Spot Size: 11 -25 μm (standard 532nm)
 Focus Len: 102 mm flat telecentric type

#### Laser System

Laser Type: Diode pumped Q-switched Nd: YAG laser

Output Power: 3W (Average @, 7.5 KHz)

Wavelength: Standard 532nm

● Mode: TEMoo

• Frequency Range: 1-100KHz

Pulse Width: 70ns (nominal) @ 1KHz

Power Measurement: Thermal pickup

# X/Y Part Positioning

Type: Dual carriage mounted on brushless DC servo

motor stages

X Axis: Driven by high speed linear motor (carriages)

- XY Resolution: 1um

• Travel Speed: 600 mm/s

Prober: High speed linear motor with pneumatic

counter balance

Theta Control: Motorized theta control
 Alignment: Pattern recognition based alignment

Part Transfer: Pneumatically controlled pick and

place arms

Part Load/Unload: Dual set of magazines with elevators

#### Measurement System

Dual Mode: Force Current & Force Voltage

• Range:  $0.1\Omega \sim 30 M\Omega$ ,  $10 m\Omega$  Optional

Accuracy: 0.02% Midrange

Repeatability: 0.01% Midrange
 Resolution: 0.005%

● Measurement Time: 50 µsec

Calibration Standards: 6 pcs 0.01%

Guard Drive Current: 100 mA

Guard Offset: 1 mV

# **Physical Characteristics**

• Dimensions: 1820 mm x 1070 mm x 2050 mm





# **Utilities Requirements**

• Power: 220 V AC, single phase, 10A ( 50/60Hz)

● Air: 80~100 psi / flow rate 10 cfm

 Vacuum: 100 csm factory vacuum for debris removal and substrates retention

#### Controller

Intel Core 2 duo processor for main application

Pentium processor for trimmer application

#### **Special Features**

 Wireless probe card with very low contact resistance connectors and shielded cables for high measurement stability

Advance sensors to detect part breakage along two edges

 Rotary control with two sets of magazines to reduce the machine idle time

 Improved pick-n-place design for efficient pick up and placing of substrates

#### Software

 LTS2010 software with an easy-to-use interface running in Windows XP

# **Switching Matrix**

• Pins per Card: 16

• Lines per Pin: 3 (Force, Sense or Guard)

• Cards per System: 12 pcs

Switch Type: Dry Reed Relay

Contact Life: 1 Billion Cycles

- Contact Life. I Billion by

• Insulation: > 10  $G\Omega$ 

Switching Time: 200 μsec



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